



EUROPRACTICE



DfMMM
NoE PATENT

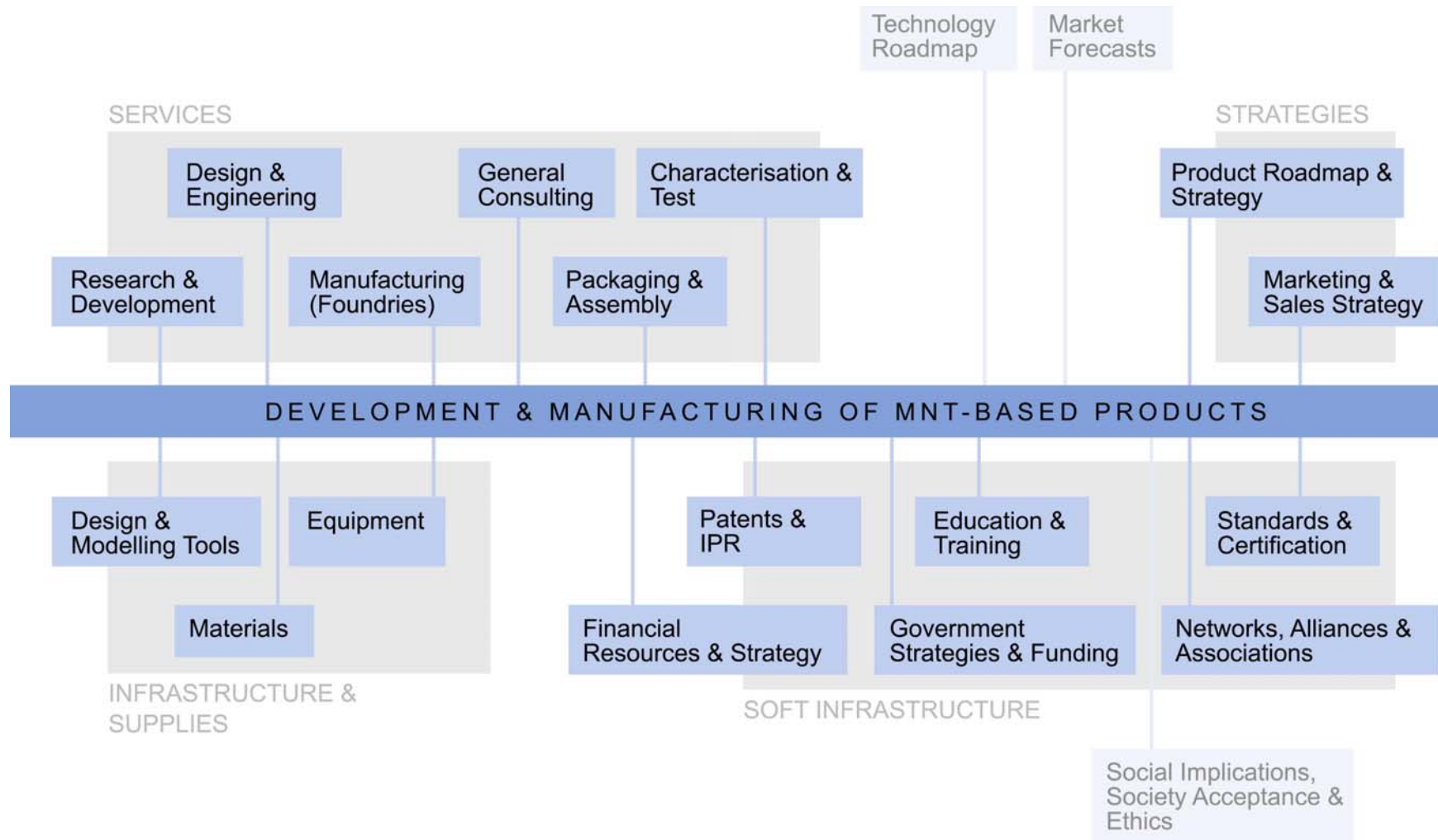
EUROPRACTICE Service Clusters

-

Opportunities in FP7

Patric Salomon

4M2C PATRIC SALOMON GmbH - enablingMNT

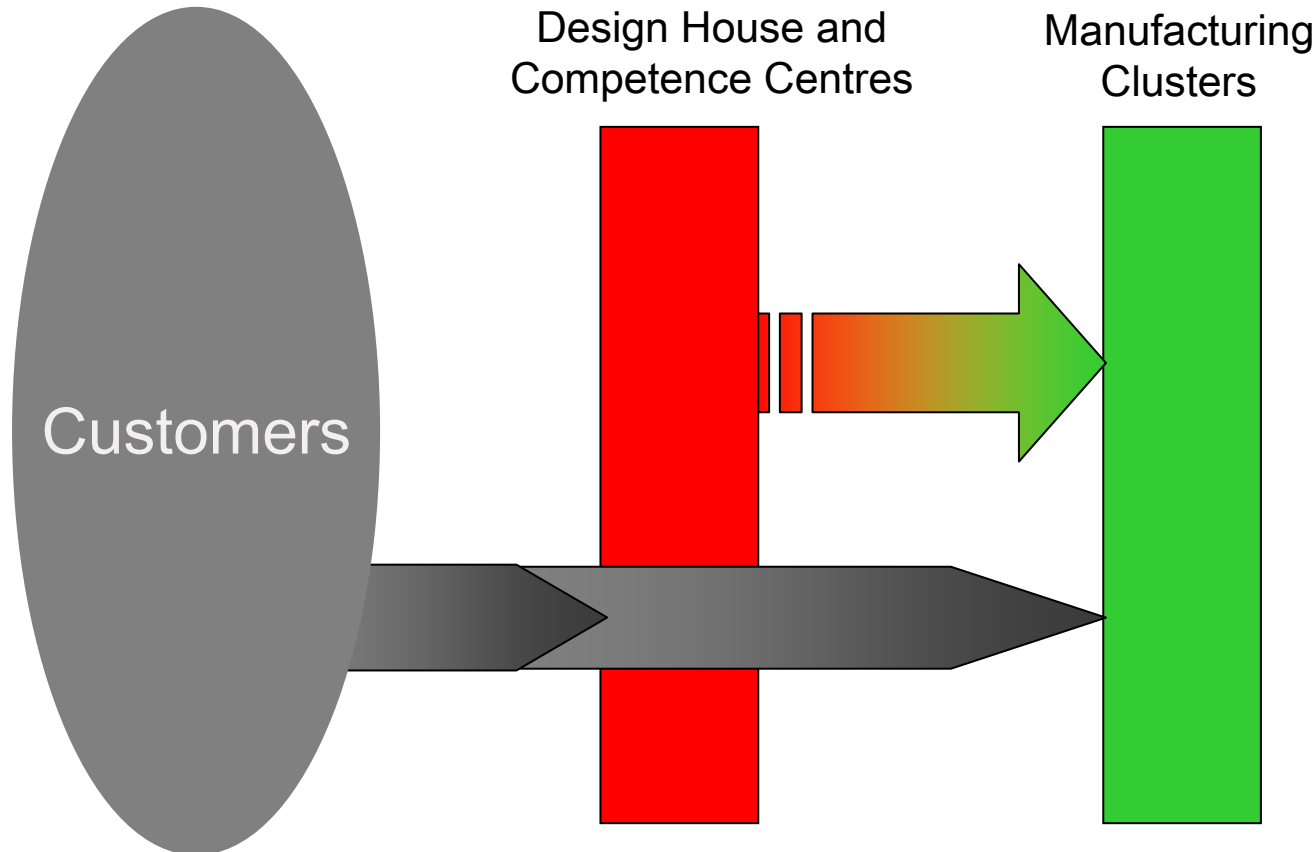


The Major European Community Programme promoting:
“Access to microelectronics technologies for industrial competitiveness in Europe”

- **Microsystems**
- Training
- Integrated Circuits
- IC & Microsystems Software

The BRIDGE project (2004-2007):

- **EUROPRACTICE Marketing and Networking**
- **Support to Eastern Organisations**
- **Partners: RAL (coordinator), YOLE, 4M2C**
- **Subcontractors: BIA, IMT**



NEW in 2005: Integrated Projects offering Services
NEW in 2006: include other Service Projects and "old" Service Providers
in Europractice Family



EUOPRACTICE



Search EUOPRACTICE Website →

EUOPRACTICE is a European Commission initiative, funded by the EU Information Society Technologies (IST) Work Program. The aim is to improve the competitiveness of European industry by the adoption of advanced electronics technologies. "EUOPRACTICE" has become internationally recognised as a quality brand name for European service-type projects in the Microsystems and Microelectronics fields.

In 2006, the EC introduced new Microsystems service actions and research activity Integrated Projects (IP's). The activities of the new IP's together with the work of existing service providers comprise the "new EUOPRACTICE".

Click on the logos below for more information on the projects comprising the new EUOPRACTICE family.



EUOPRACTICE Coordination.

BRIDGE provides a co-ordination role by providing a framework for cooperation between the EUOPRACTICE partners.

- [Click for more information](#)

EUOPRACTICE News.

For information on EUOPRACTICE projects plus MEMS technologies, applications and developments.

- [Latest edition \(August 2006\)](#)
- [EUOPRACTICE News Archive](#)

Microsystems Suppliers.

Microsystems-suppliers.com is a database of companies that offer microsystems services, products, equipment and materials.

- www.microsystems-suppliers.com

Next-Generation Nanoelectronics Components and Electronics Integration, Call 1: **specific bullet on Support measures will complement the research activities:**

- Access to prototyping, design expertise and training for SME's.
- Access for universities and research institutes to affordable industrial design tools, state-of-the-art technologies for prototyping and training.
- Roadmapping, benchmarking and definition of selection criteria for the industrial use of "Beyond CMOS" technologies.
- Stimulating the interest of young people in electronics / multidisciplinary careers.
- Supporting the development of RTD strategies through roadmapping, consensus building, coordination with Member States, and international cooperation.
- CSA aiming at coordinating related national or regional and EU-wide RTD programmes or activities.



Organic and large-area electronics ,

Call 1: specific bullet on:

Support measures will include access to advanced manufacturing and design competences, training and education for organic and large area electronics, joint user assessment of prototype equipment from European suppliers and will develop synergies between the electronics and the printing sectors on circuit design, manufacturing equipment and standardisation.

Photonic components and subsystems,

Call 2: specific bullet on Support measures

Access to centres of expertise and foundries to facilitate the deployment of advanced technologies.

Raising the interest of young people in photonics careers, and stimulating cross-national schemes for graduate education.

Supporting the development of RTD strategies through roadmapping, consensus building, coordination with Member States, and international cooperation.

Micro/nanosystems, Call 2: specific bullet on:

Support measures will ensure broad access to micro/nanosystems manufacturing technologies, in particular by SMEs, identify training and education needs of the area proposing appropriate measures and establish specific measures aiming at coordination and dissemination of smart systems integration RTD at European level.

* The information presented in these 3 slides is 'preliminary'

